

Electronic Patent Application Fee Transmittal

| Application Number: | 10568147 | | | |
|---|--|----------|--------|----------------------|
| Filing Date: | 13-Feb-2006 | | | |
| Title of Invention: | Abrasive compounds for semiconductor planarization | | | |
| First Named Inventor/Applicant Name: | Kanshi Chinone | | | |
| Filer: | LEE C WRIGHT/Akemi Ferebee | | | |
| Attorney Docket Number: | 062110 | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 3 months with \$0 paid | 1253 | 1 | 1110 | 1110 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 1110 |